

#### 1, Physical Dimensions(size of 1812)

Part Number	А		В		С		D	Morling	
	Min	Max	Min	Max	Min	Max	Min	Marking	
K1812L300/12DR	4.37	4.73	3.07	3.41	0.60	1.00	0.30	T300	

# Top and Bottom View Marking

Unit:mm



Side View

### 2、Electrical Characteristics

Part Number	I <sub>H</sub> (A)	I <sub>T</sub> (A)	V <sub>max</sub> (V)	I <sub>max</sub> (A)	Ttrij (Max time Current(A)		Pd <sub>typ</sub> (W)	${f R}_{min} \ (\Omega)$	$\begin{array}{c} R1_{max} \\ (\Omega) \end{array}$
K1812L300/12DR	3.00	6.00	12	100	8.0	5.00	1.2	0.012	0.060

 $I_{\rm H}$ : Holding Current: maximum current at which the device will not trip in 25 °C still air.

I<sub>T</sub>: Tripping Current minimum current at which the device will trip in  $25^{\circ}$ C still air.

V<sub>max</sub>: Maximum voltage device can withstand without damage at rated current.

I max: Maximum fault current device can withstand without damage at rated voltage.

T trip: Maximum time to trip(s) at assigned current.

Pd typ: Rated working power.

R min: Minimum resistance of device prior to trip at  $25 \,^{\circ}$ C.

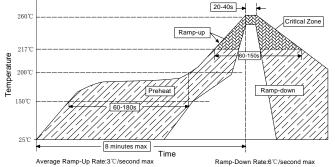
R1 max: Maximum resistance of device is measured one hours post reflow at 25°C.

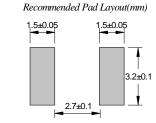
Noted: All electrical function test is conducted after PCB mounted.

### 3、Thermal Derating

K1812L300/12DR	Maximum ambient operating temperature									
	-40℃	-20°C	0°C	25℃	40°C	50℃	60℃	70°C	85℃	
Hold Current(A)	4.40	3.90	3.50	3.00	2.60	2.30	2.10	1.80	1.50	
Trip Current(A)	8.80	7.80	7.00	6.00	5.20	4.60	4.20	3.60	3.00	

### 4. Solder Reflow Recommendations





Notes: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

## 5, Package Information

Packing quantity:1500PCS/Reel

Note:Reel packaging per EIA-481-1 standard